IN THE CLAIMS:

- 1. (Previously Presented) A curable silicone composition comprising:
- (A) an organopolysiloxane represented by the siloxane unit formula (1) given below and having at least two univalent organic groups that contain epoxy groups and are free of aromatic rings:

$$[R^{1}_{3}SiO_{10}]_{a}[R^{2}_{2}SiO_{20}]_{b}[R^{3}SiO_{30}]_{c}$$

$$(1)$$

where R^1 , R^2 , and R^3 are univalent organic groups, at least two of which are univalent organic groups which contain epoxy groups and are free of aromatic rings; more than 20 mole % of R^3 are aryl groups; a+b+c=1; on average, "a" satisfies the following condition: $0 \le a \le 0.8$; on average, "b" satisfies the following condition: $0 \le b \le 0.8$; and, on average, "c" satisfies the following condition: $0.2 \le c \le 1.0$;

(B) a linear-chain organopolysiloxane having at least two univalent organic groups that contain phenolic hydroxyl groups, where said linear-chain organopolysiloxane is represented by the following formula (2):

$$R^{7}_{3}SiO(R^{8}_{2}SiO)_{m}SiR^{7}_{3}$$
 (2)

where R⁷ and R⁸ may be the same or different and represent univalent organic groups of which, at least two are univalent organic groups having phenolic hydroxyl groups; and "m" is an integer having a value of 0 to 1000; and

- (C) a curing accelerator.
- (Original) The curable silicone composition of Claim I, further comprising a filler
 (D).

- (Previously Presented) The curable silicone composition of Claim 1, where component (A) is liquid.
- 4. (Previously Presented) The curable silicone composition of Claim 1, where in the siloxane unit formula (1), $0 < a \le 0.8$; and b=0.
- (Cancelled).
- (Previously Presented) The curable silicone composition of Claim 1, where component (B) is an organopolysiloxane represented by the following formula (4):

$$Z-(CH_3)_2SiO(CH_3)_2Si-Z$$
 (4)

where Z is 3-(m-hydroxyphenyl)propyl group.

- 7. (Previously Presented) The curable silicone composition of Claim 1, where component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) in an amount of 0.01 to 100 parts by weight for each 100 parts by weight of component (A).
- 8. (Previously Presented) The curable silicone composition of Claim 1, where the epoxy group of component (A) is a glycidoxy group or a 2,4-epoxycyclohexyl group.
- (Previously Presented) The curable silicone composition of Claim 1, which is in a liquid or a paste-like form.
- (Previously Presented) A cured product obtained by curing the curable silicone composition according to Claim 1.
- 11. (Cancelled).

- (Previously Presented) The curable silicone composition of Claim 2, where component (A) is liquid.
- 13. (Previously Presented) The curable silicone composition of Claim 2, where in the siloxane unit formula (1), $0 < a \le 0.8$; and b=0.
- 14. (Cancelled).
- 15. (Previously Presented) The curable silicone composition of Claim 2, where component (B) is an organopolysiloxane represented by the following formula (4):

$$Z-(CH_3)_2SiO(CH_3)_2Si-Z$$
 (4)

where Z is 3-(m-hydroxyphenyl)propyl group.

- 16. (Previously Presented) The curable silicone composition of Claim 2, where component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) in an amount of 0.01 to 100 parts by weight for each 100 parts by weight of component (A).
- 17. (Previously Presented) The curable silicone composition of Claim 2, where the epoxy group of component (A) is a glycidoxy group or a 2,4-epoxycyclohexyl group.
- 18. (Previously Presented) The curable silicone composition of Claim 2, which is in a liquid or a paste-like form.